

ABSTRACT OF THE DISCLOSURE

Bump formation method and wire bonding method including a step of forming a ball on the tip end of a wire that passes through a capillary and joining this ball to an electrode pad so as to make a press-bonded ball. In the next step, the capillary is raised and moved horizontally so that the bottom flat portion of the capillary faces the press-bonded ball. Then, the capillary is lowered and the press-bonded ball is pressed, thus forming a first bump. Next, the capillary is raised and moved horizontally in a direction that is opposite from the previous horizontal-direction, thus positioning the flat portion of the capillary to face the first bump. Then, the capillary is lowered, and the wire is bent and pressed against the surface of the first bump so as to form a second bump. The wire is then cut from the second bump.